MARKING CONFIRMED VISUALLY. ELECTRIC CHARACTERISTICS CONTACT RESISTANCE RESISTANCE RECOGOTIZED FEST CURRENT IMA. DOPEN VOLTAGE 20 mV AC MAX, TEST CURRENT IMA. SET CURRENT IMA. DOPEN VOLTAGE 20 mV AC MAX, TEST CURRENT IMA. SET CURRENT IMA.	APPLICABLE			microSD Memory Card	Speci	fications Ve	er 1.10					
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RATIND VOLTAGE AC 125V HUMBORY RANGE 95/MAXIMUM (NON-CONDENSIND) SPECIFICATIONS ITEM TEST METHOD REQUIREMENTS OT AT CONSTRUCTION GENERAL VISUALLY AND BY MEASURING INSTRUMENT. ACCORDING TO DRAWING. X X X X X X X X X X X X X X X X X X X				-25 °C TO +85 °C (NO	TE1)) TEMPERATUR		NGE	-40 °C TO +85 °C			
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